



## Material Content Data Sheet



<b>Sales Product Name</b>				SAK-TC1782F-320F180HR BA		<b>Issued</b>		19. July 2018	
<b>MA#</b>				MA001225628					
<b>Package</b>				PG-LQFP-176-20		<b>Weight*</b>		2050.51 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	65.128	3.18	3.18	31762	31762	
leadframe	inorganic material	phosphorus	7723-14-0	0.155	0.01		76		
	non noble metal	zinc	7440-66-6	0.620	0.03		302		
	non noble metal	iron	7439-89-6	12.403	0.60		6049		
wire	non noble metal	copper	7440-50-8	503.632	24.56	25.20	245613	252040	
	noble metal	palladium	7440-05-3	0.041	0.00		20		
	non noble metal	copper	7440-50-8	4.066	0.20	0.20	1983	2003	
encapsulation	organic material	carbon black	1333-86-4	7.026	0.34		3426		
	plastics	epoxy resin	-	189.701	9.25		92514		
	inorganic material	silicondioxide	60676-86-0	1208.466	58.93	68.52	589350	685290	
leadfinish	noble metal	palladium	7440-05-3	0.142	0.01		69		
	noble metal	silver	7440-22-4	0.124	0.01		61		
	noble metal	gold	7440-57-5	0.228	0.01		111		
	non noble metal	nickel	7440-02-0	4.888	0.24	0.27	2384	2625	
plating	noble metal	silver	7440-22-4	0.928	0.05		453		
	noble metal	gold	7440-57-5	1.705	0.08		832		
	noble metal	palladium	7440-05-3	1.061	0.05		517		
	non noble metal	nickel	7440-02-0	36.558	1.78	1.96	17829	19631	
glue	plastics	epoxy resin	-	3.409	0.17		1662		
	noble metal	silver	7440-22-4	10.226	0.50	0.67	4987	6649	
*deviation	< 10%		Sum in total:			100.00		1000000	

### Important Remarks:

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